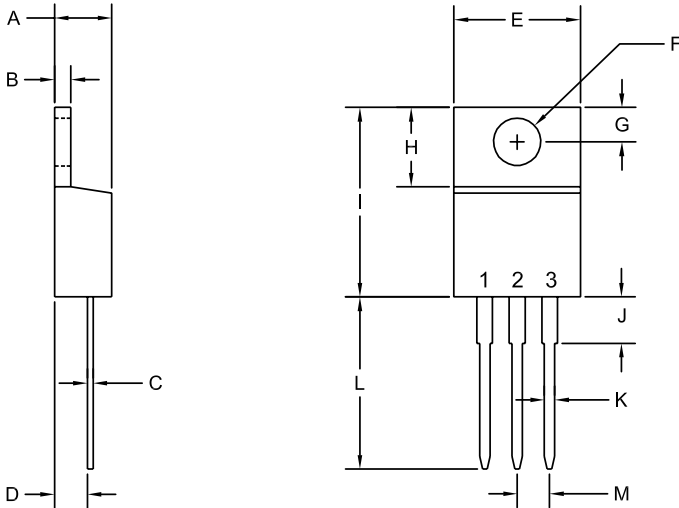


Package Details - TO-220

Mechanical Drawing



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.170	0.190	4.31	4.82
B	0.045	0.055	1.15	1.39
C	0.013	0.026	0.33	0.65
D	0.083	0.107	2.10	2.72
E	0.394	0.417	10.01	10.60
F (DIA)	0.140	0.157	3.55	4.00
G	0.100	0.118	2.54	3.00
H	0.230	0.270	5.85	6.85
I	0.560	0.625	14.23	15.87
J	-	0.250	-	6.35
K	0.025	0.038	0.64	0.96
L	0.500	0.579	12.70	14.70
M	0.090	0.110	2.29	2.79

TO-220 (REV: R2)

LEAD CODE:

R2

TRIAC

- 1) MT1
- 2) MT2
- 3) GATE

SCR

- 1) CATHODE
- 2) ANODE
- 3) GATE

TRANSISTOR

- 1) BASE
- 2) COLLECTOR
- 3) EMITTER

Note: TAB is Common to Pin 2

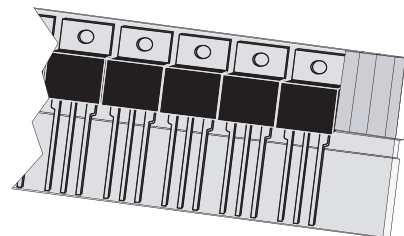
Packing Information

Standard: Bulk

Devices are bulk packed in white corrugated box with black conductive coating (surface resistivity of $<10^5$ ohms per square).

Standard Packing Quantity: 500

Sleeve Packing Quantity: 50



TO-220 Antistatic Sleeve

CentralTM
Semiconductor Corp.
www.centrasemi.com

R0 (9-August 2004)

Material Composition Specification

TO-220 Case



Device average mass 1.89 g
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.3%	5.67	Si	7440-21-3	0.3%	5.67	3,006
bond wire	aluminum	0.14%	2.55	Al	7429-90-5	0.14%	2.55	1,352
leadframe	Cu alloy	66.89%	1261.86	Cu	7440-50-8	66.79%	1,260	667,944
				Fe	7439-89-6	0.003%	0.06	32
				P	7723-14-0	0.1%	1.8	954
die attach	high temperature solder	0.33%	6.21	Pb	7439-92-1	0.3%	5.74	3,043
				Sn	7440-31-5	0.02%	0.31	164
				Ag	7440-22-4	0.01%	0.16	82
encapsulation*	EMC	31.81%	600	silica	7631-86-9	23.22%	438	232,190
				epoxy resin	Proprietary	7.32%	138	73,156
				Sb ₂ O ₃	1309-64-4	0.64%	12	6,361
				TBBA	79-94-7	0.64%	12	6,361
	EMC GREEN	31.81%	600	silica	7631-86-9	23.86%	450	238,552
				epoxy resin	Proprietary	4.93%	93	49,301
				epoxy polymer	Proprietary	2.39%	45	23,855
				Sb ₂ O ₃	1309-64-4	0.54%	10.2	5,406
plating**	tin/lead process	0.54%	10.1	Sn	7440-31-5	0.43%	8.08	4,283
				Pb	7439-92-1	0.11%	2.02	1,071
	100% tin process	0.54%	10.1	Sn	7440-31-5	0.54%	10.1	5,354

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R3 (20-July 2016)